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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1 - 4 (Cancelled)

- 5. (Currently amended) An expansive element in a thermoelastic design that is made from any functionally suitable a material or combinations of materials selected from a group including-silicides and carbides of titanium the material or combination of materials being selected to have one or more of the following properties:
 - (a) a resistivity between $0.1\mu\Omega m$ and $10.0\mu\Omega m$;
 - (b) chemically inert in air:
 - (c) chemically inert in the chosen ink; and
 - (d) depositable by CVD, sputtering or other thin film deposition technique.
- 6. (Cancelled)
- 7. (Currently amended) An expansive element in a thermoelastic design that is made from any functionally suitable a material or combinations of materials selected from a group including: borides, silicides, carbides and nitrides of tantalum, molybdenum, niobium, chromium, tungsten, vanadium, and zirconium, and having one or more of the following properties:
 - (e) a resistivity between $0.1\mu\Omega m$ and $10.0\mu\Omega m$:
 - (f) chemically inert in air:
 - (g) chemically inert in the chosen ink; and
 - (h) depositable by CVD, sputtering or other thin film deposition technique.
- 8. (Cancelled)
- 9. (Currently amended) An expansive element in a thermoelastic design that is made from any functionally suitable an alloy material or combinations of alloy materials selected from the group including: borides, silicides, carbides and nitrides of titanium, tantalum, molybdenum, niobium, chromium, tungsten, vanadium, and zirconium, and having one or more of the following properties:

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- (i) a resistivity between 0.1μΩm and 10.0μΩm:
- (j) chemically inert in air;
- (k) chemically inert in the chosen ink; and
- (1) depositable by CVD, sputtering or other thin film deposition technique.
- 10. (Cancelled)